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01/28/2002

PATENT NUMBER and  
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10058473	FILING DATE 01/28/2002	CLASS 438	SUBCLASS 124	GAU 3823 2842	EXAMINER W. Fahmy
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\*\*CONTINUING DATA VERIFIED: none ME

\*\* FOREIGN APPLICATIONS VERIFIED: none ME

PG-PUB	DO NOT PUBLISH <input checked="" type="checkbox"/>	RESCIND <input type="checkbox"/>
Foreign priority claimed	<input type="checkbox"/> yes <input checked="" type="checkbox"/> no	ATTORNEY DOCKET NO TS01-1063
35 USC 119 conditions met	<input type="checkbox"/> yes <input checked="" type="checkbox"/> no	
Verified and Acknowledged Examiners's initials	ME	
TITLE : Enhanced adhesion strength between mold resin and polyimide		

U.S. DEPT. OF COMM./PAT. & TM.-PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg. Print Fig.
<input type="checkbox"/> TERMINAL DISCLAIMER		Application Examiner	
		PREPARED FOR ISSUE	
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